

Product Terratek® BD8220

Product Description Proprietary blend of natural and synthetic biodegradable polyesters suitable for injection molding. This resin is made from polymers which pass industry standards for Industrial and Home composting. Parts that include living hinge features have been achieved with this resin, results will vary dependent on part design.

Renewable Content	
Biobased content (ASTM D6866)	30%
Biomass content (by weight)	33%

Property	Test Method	Value
Specific Gravity	ASTM D792	1.31
Melt Index (190°C / 2.16 kg)	ASTM D1238	14 g/10 min
Tensile Strength (at Yield)	ASTM D638	3,500 psi
Elongation (at Max)	ASTM D638	18.0%

Drying Conditions

Moisture level: at or below 0.04% (400 ppm)
 Method: Karl Fischer; if using a loss in weight analyzer, contact Green Dot for more information.
 Drying conditions: Desiccant dryer 140°F for 2 to 4 hours or until the recommended moisture level is reached

ATTENTION: Moisture in Terratek® BD resins may result in hydrolysis which can cause brittleness, loss in strength, and reduction in melt strength, in addition to potentially impacting the shelf life of finished parts.

Packaging and Storing

This resin is typically packaged in a sealed plastic or foil lined box, drum, or gaylord. The product should be stored in a cool, dry, and sanitary area to achieve maximum stability.

Molding Recommendations

Terratek® resins can be processed on conventional molding equipment. Follow standard purging process with a polyolefin or purge compound, such as Dyna-Purge, etc. Melt temperature of the resin should remain below 400°F.

Feed Zone	280°F to 320°F
Middle Zones	320°F to 360°F
Front Zones	320°F to 360°F
Nozzle/Die	320°F to 360°F
Mold	80°F to 120°F

The information and recommendations in this sheet are based on our experience and analysis using standard procedures, and are believed to be accurate and reliable. However, they serve merely as typical guides, and are presented in good faith for the benefit of our customers. No guarantee, expressed or implied, is made regarding accuracy of the analysis, patent infringement, liabilities, or risks involved from the application